

ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit packaging system includes:
5 providing an integrated circuit substrate having a non-active side and an active side; forming
a recess in the integrated circuit substrate from the non-active side exposing a first contact
and a second contact with the first contact and the second contact along the active side;
forming a first via, having a first via extension extended beyond the non-active side and an
opening at the non-active side, within the recess; forming a barrier liner within the opening
10 with the barrier liner exposed beyond the non-active side; and forming a second via over the
barrier liner and within the opening of the first via with the second via exposed beyond the
non-active side.

Fig. 2